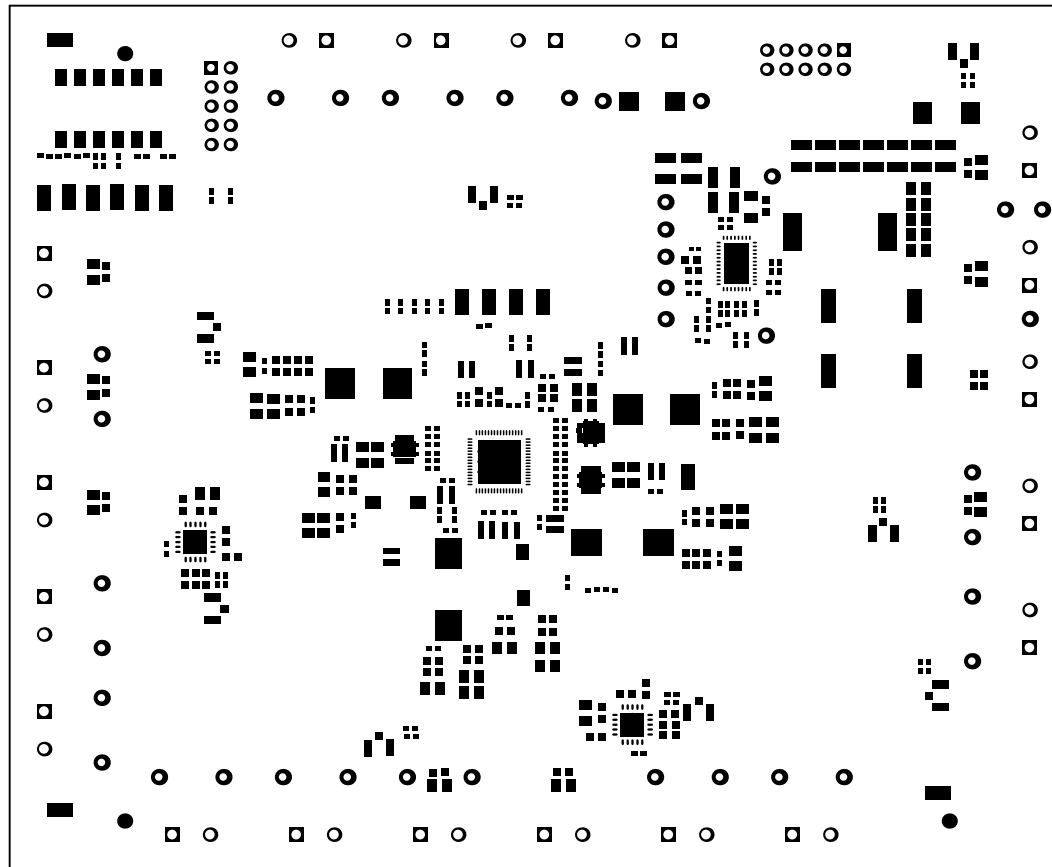
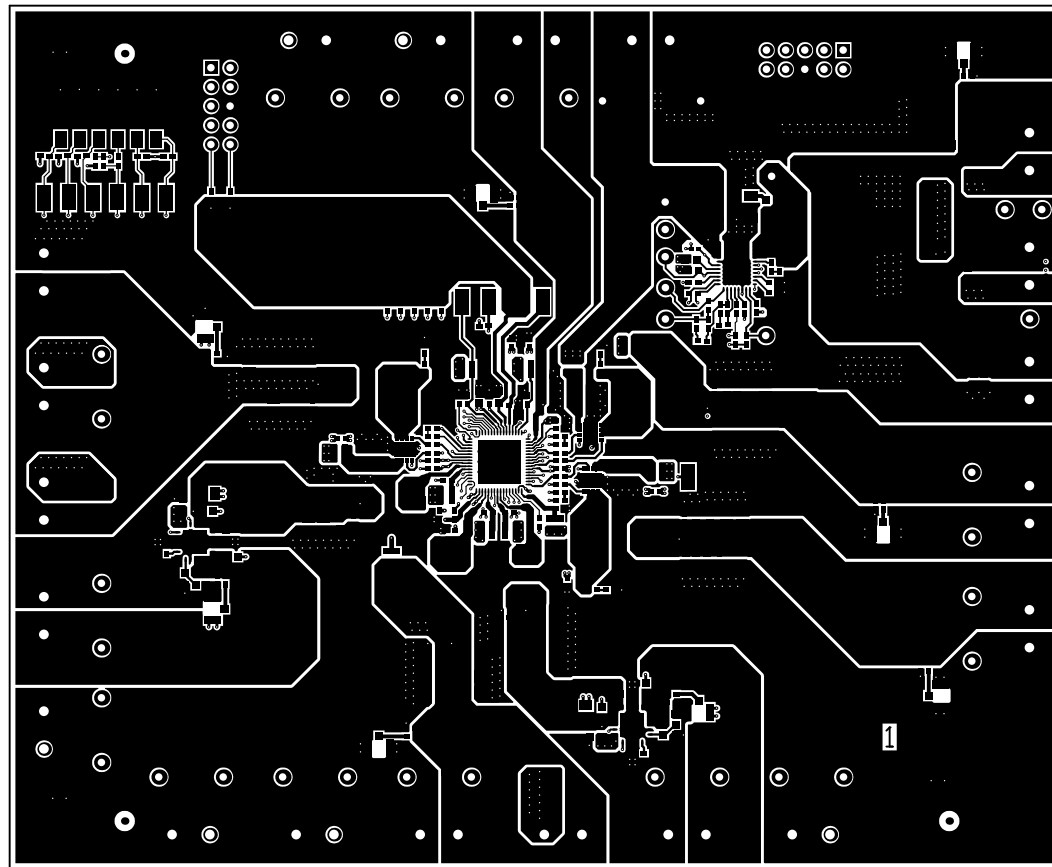


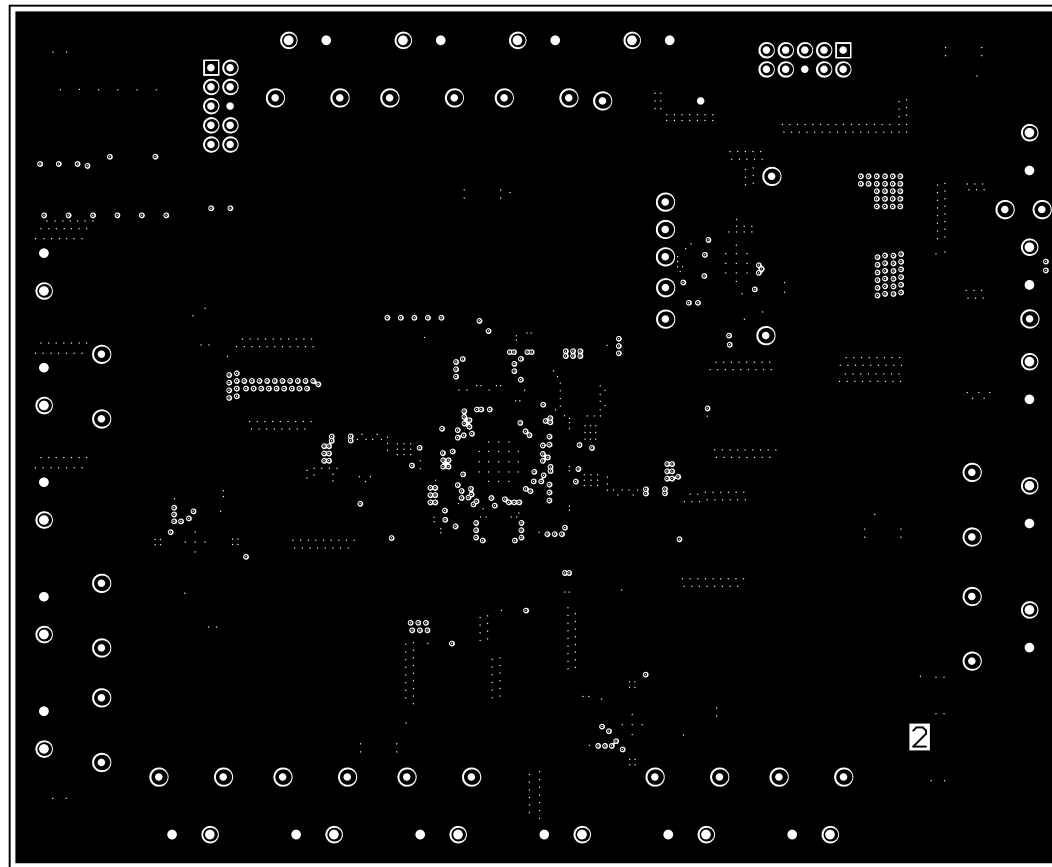
| | | | |
|----------------------------------|-----------------------|------------|--------------------------------|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: PMP12004- | REV: RevA | SUN REV: Not In VersionControl |
| LAYER NAME = Top Overlay | TID #: PMP12004-HE | | |
| | GENERATED : 3/30/2016 | 2:19:00 AM | TEXAS INSTRUMENTS |



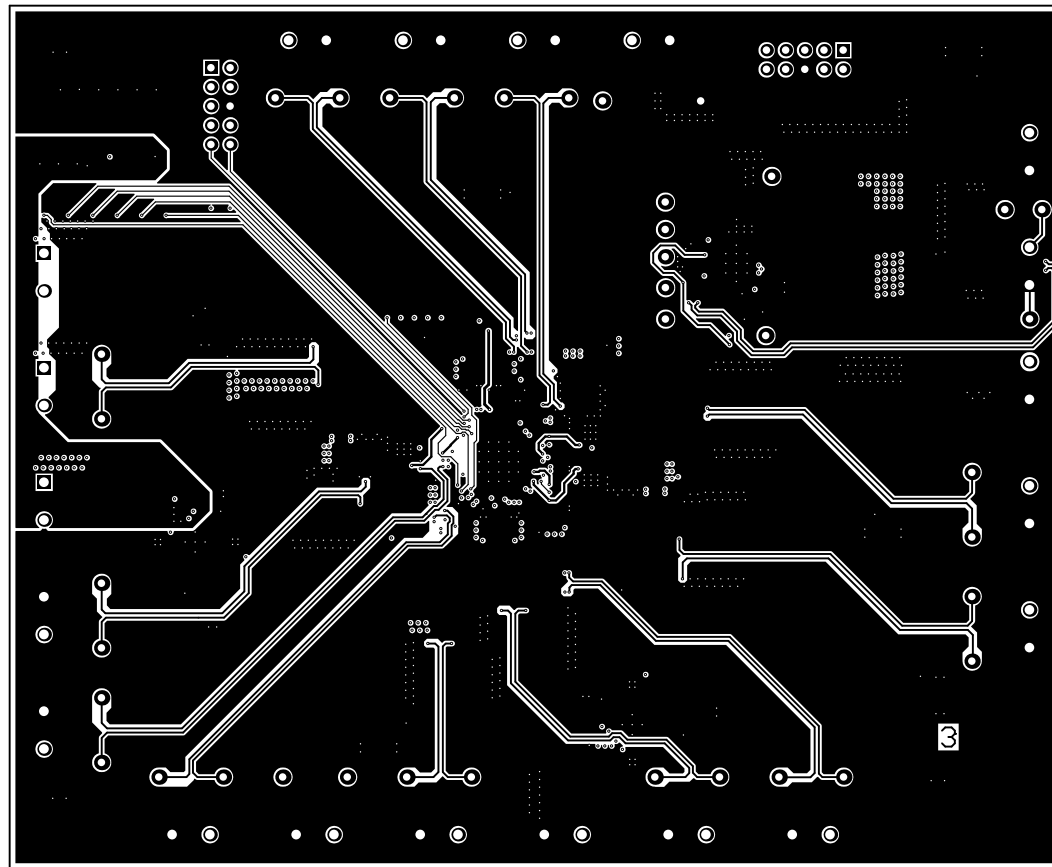
| | | | |
|----------------------------------|----------------------------------|-------------------|--------------------------------|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: PMP12004- | REV: RevA | SUN REV: Not In VersionControl |
| LAYER NAME = Top Solder | TID #: PMP12004-HE | | |
| | GENERATED : 3/30/2016 2:19:02 AM | TEXAS INSTRUMENTS | |



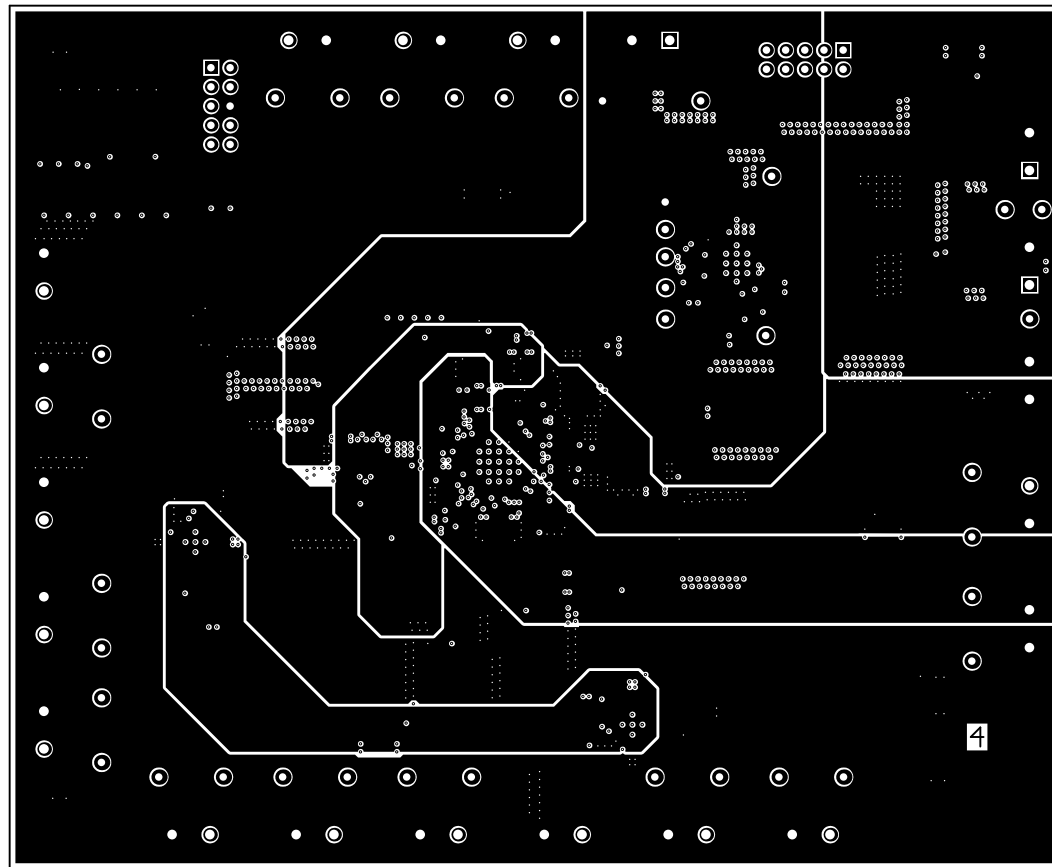
| | | | |
|----------------------------------|----------------------------------|-------------------|--------------------------------|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: PMP12004- | REV: RevA | SUN REV: Not In VersionControl |
| LAYER NAME = Top Layer | TID #: PMP12004-HE | | |
| | GENERATED : 3/30/2016 2:19:04 AM | TEXAS INSTRUMENTS | |



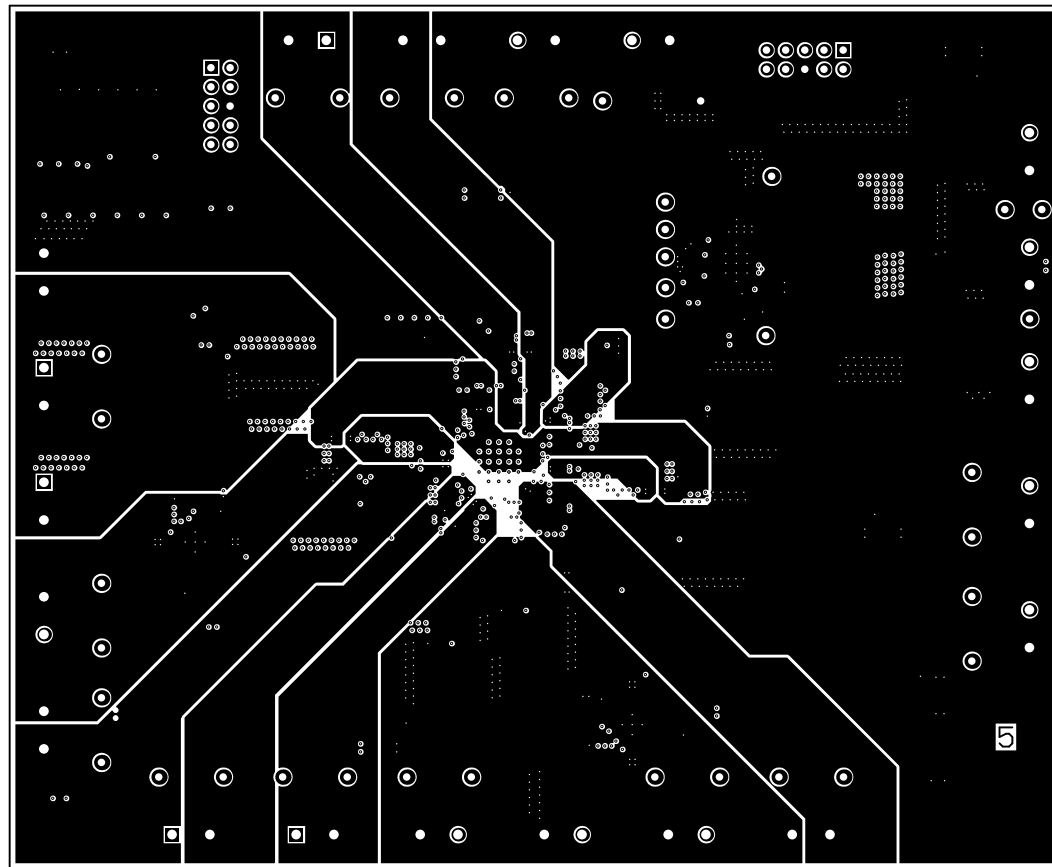
| | | | |
|----------------------------------|----------------------------------|-------------------|--------------------------------|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: PMP12004- | REV: RevA | SUN REV: Not In VersionControl |
| LAYER NAME = GND | TID #: PMP12004-HE | | |
| | GENERATED : 3/30/2016 2:19:05 AM | TEXAS INSTRUMENTS | |



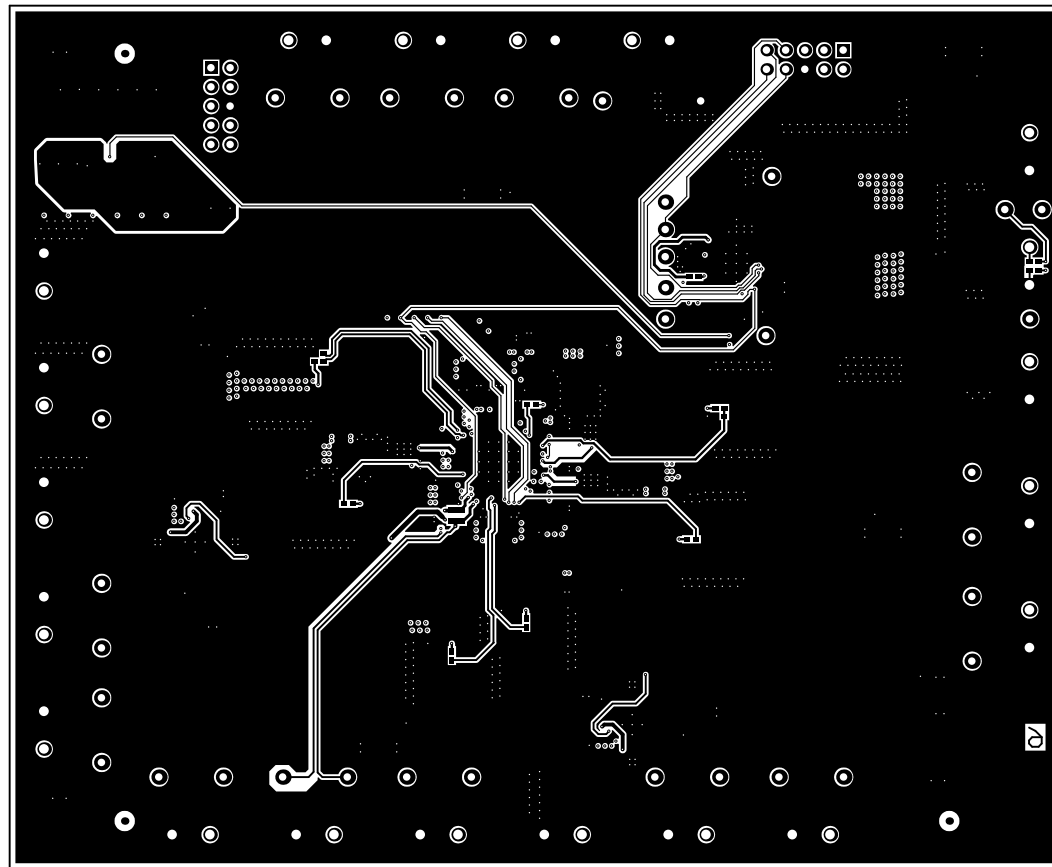
| | | | |
|----------------------------------|----------------------------------|-------------------|--------------------------------|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: PMP12004- | REV: RevA | SUN REV: Not In VersionControl |
| LAYER NAME = Signal Layer 1 | TID #: PMP12004-HE | | |
| | GENERATED : 3/30/2016 2:19:06 AM | TEXAS INSTRUMENTS | |



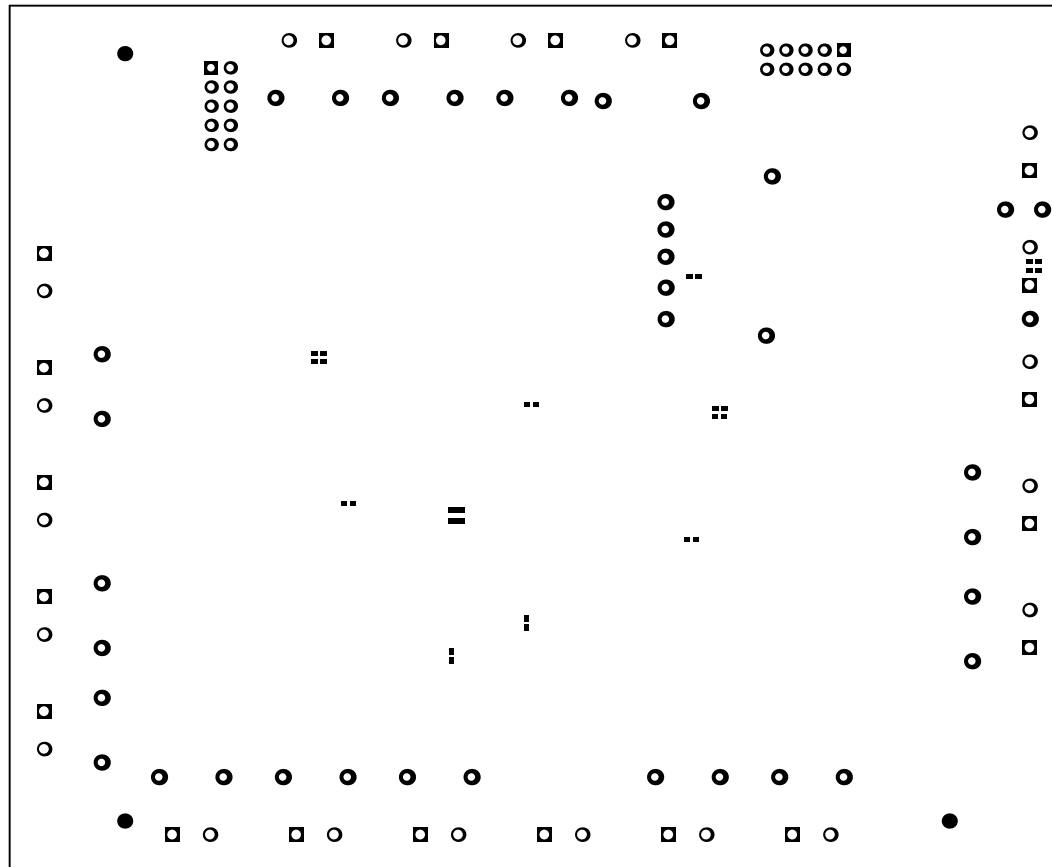
| | | | |
|----------------------------------|----------------------------------|-------------------|--------------------------------|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: PMP12004- | REV: RevA | SUN REV: Not In VersionControl |
| LAYER NAME = Signal Layer 2 | TID #: PMP12004-HE | | |
| | GENERATED : 3/30/2016 2:19:08 AM | TEXAS INSTRUMENTS | |



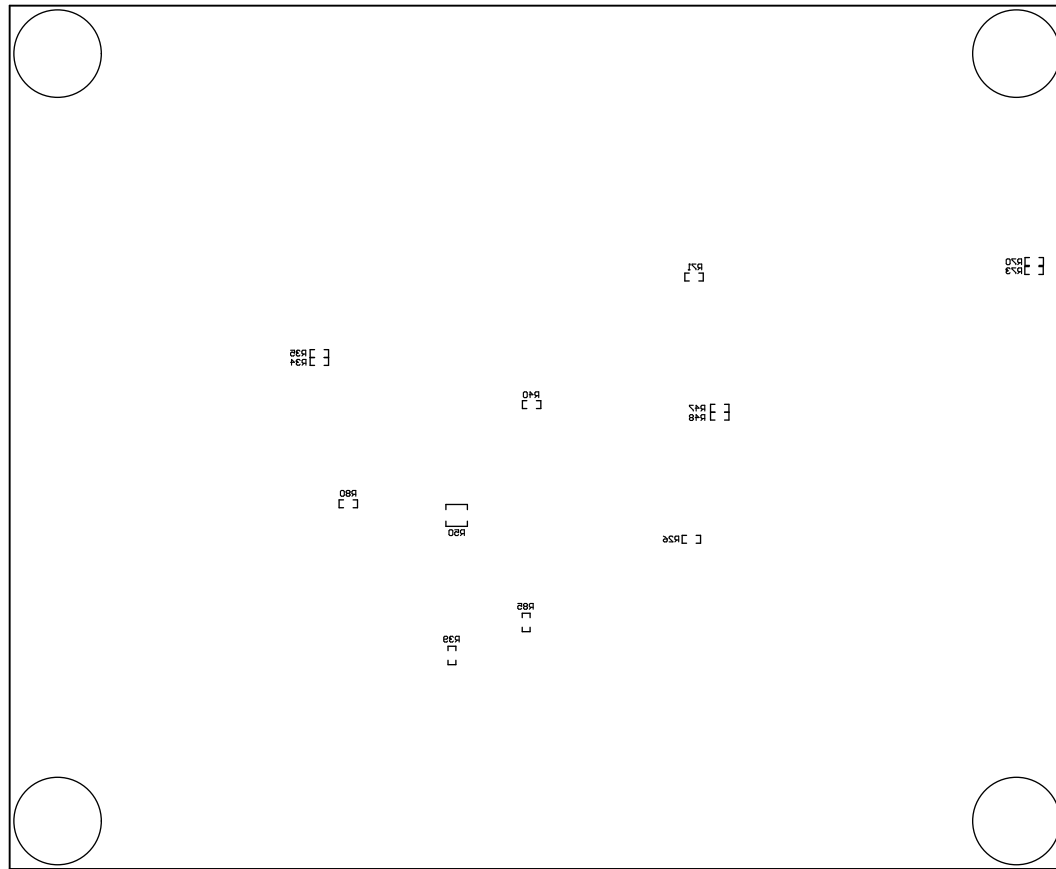
| | | | |
|----------------------------------|----------------------------------|-------------------|--------------------------------|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: PMP12004- | REV: RevA | SUN REV: Not In VersionControl |
| LAYER NAME = PWR Split | TID #: PMP12004-HE | | |
| | GENERATED : 3/30/2016 2:19:09 AM | TEXAS INSTRUMENTS | |



| | | | |
|----------------------------------|----------------------------------|-------------------|--------------------------------|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: PMP12004- | REV: RevA | SUN REV: Not In VersionControl |
| LAYER NAME = Bottom Layer | TID #: PMP12004-HE | | |
| | GENERATED : 3/30/2016 2:19:11 AM | TEXAS INSTRUMENTS | |

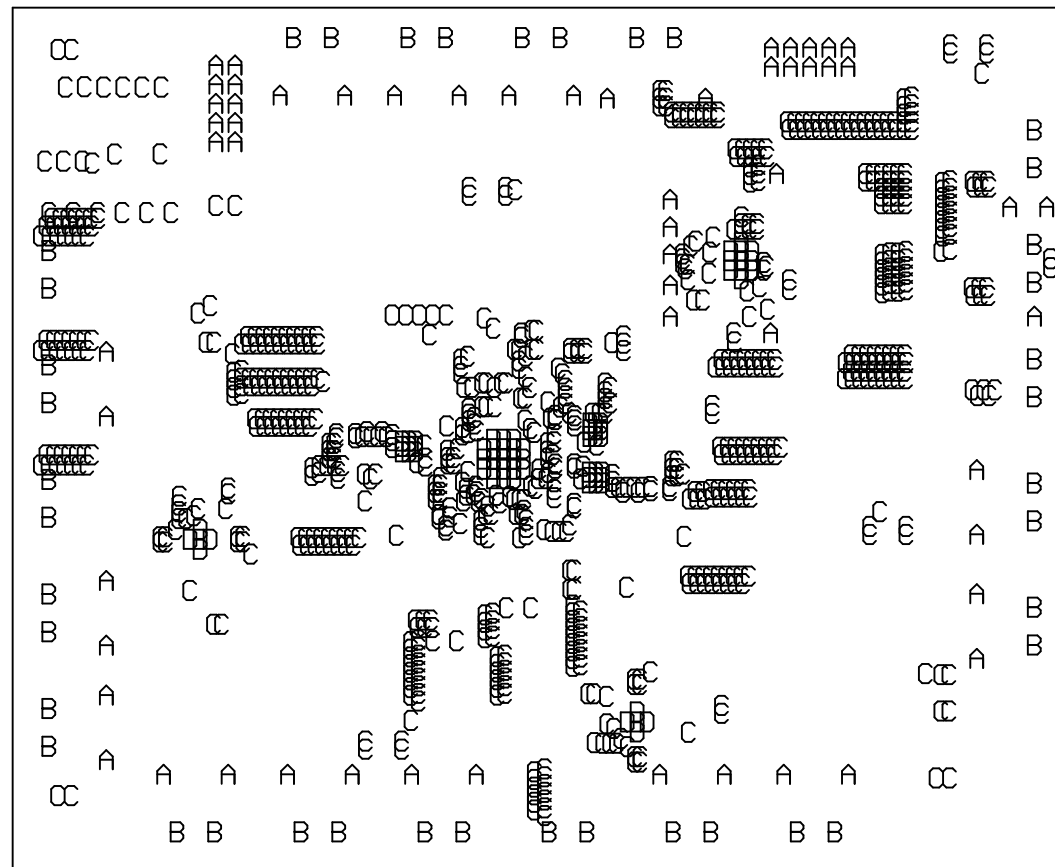


| | | | |
|----------------------------------|----------------------------------|-------------------|--------------------------------|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: PMP12004- | REV: RevA | SUN REV: Not In VersionControl |
| LAYER NAME = Bottom Solder | TID #: PMP12004-HE | | |
| | GENERATED : 3/30/2016 2:19:12 AM | TEXAS INSTRUMENTS | |

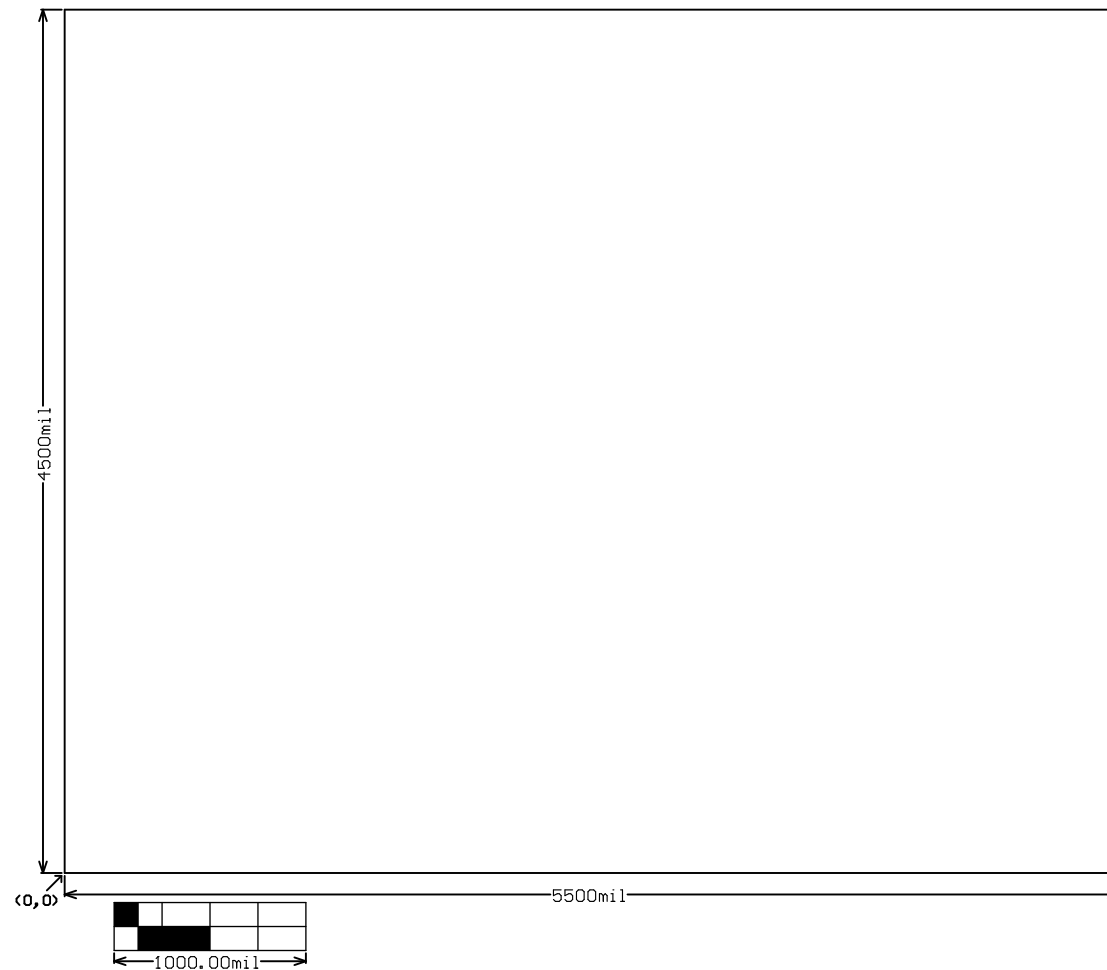


| | | | |
|----------------------------------|----------------------------------|-------------------|--------------------------------|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: PMP12004- | REV: RevA | SUN REV: Not In VersionControl |
| LAYER NAME = Bottom Overlay | TID #: PMP12004-HE | | |
| | GENERATED : 3/30/2016 2:19:14 AM | TEXAS INSTRUMENTS | |

| Symbol | Hit Count | Finished Hole Size | Plated | Hole Type | Tolerance (Mil) | Tenting |
|--------|------------|--------------------|--------|-----------|-----------------|-------------|
| C | 835 | 8.00mil (0.203mm) | PTH | Round | +0/-8 | Both Side |
| D | 69 | 8.01mil (0.203mm) | PTH | Round | +0/-8 | Bottom Side |
| A | 58 | 40.00mil (1.016mm) | PTH | Round | +/-3 | |
| B | 40 | 51.18mil (1.300mm) | PTH | Round | +/-3 | |
| | 1002 Total | | | | | |



| | | | |
|----------------------------------|-----------------------|------------|--------------------------------|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: PMP12004- | REV: RevA | SUN REV: Not In VersionControl |
| LAYER NAME = FAB | TID #: PMP12004-HE | | |
| | GENERATED : 3/30/2016 | 2:19:15 AM | TEXAS INSTRUMENTS |



| | | | |
|----------------------------------|----------------------------------|-------------------|--------------------------------|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: PMP12004- | REV: RevA | SUN REV: Not In VersionControl |
| LAYER NAME = | TID #: PMP12004-HE | | |
| | GENERATED : 3/30/2016 2:19:18 AM | TEXAS INSTRUMENTS | |

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